

# LAr R&D Progress Updates

Yichen

8/18/25



# Lab Safety and Space Management

## ► **Planned power outage 8/22-9/14**

- Complete power outage for a day or two
- 4x outages in Bldg 510 on every weekends between Friday 6pm to Sunday 3pm, starting from this weekend on 8/22
- I've briefed the group about the outage
  - Reminders of turned off all electrical devices before leaving home on Friday
- Developing a checklist to go over with all ECPs and system owners
  - LAr lab-Yichen
  - CE lab-Lingyun, Shanshan
  - Robotic testing station-Shanshan
  - 2nd storage labs, Guang

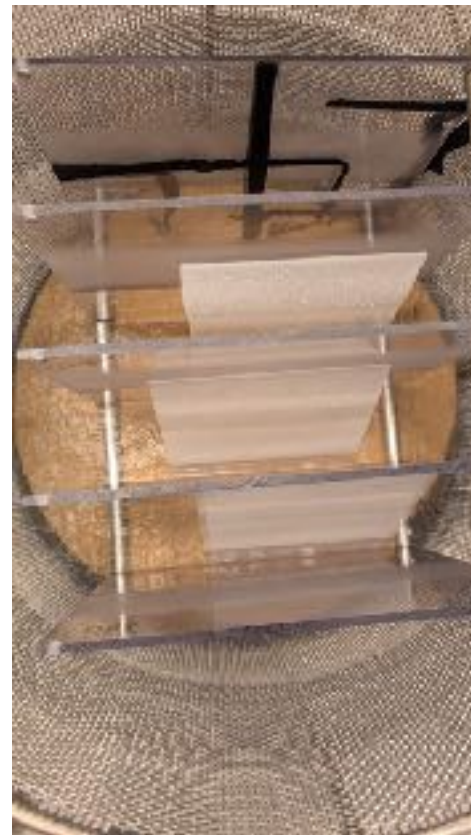
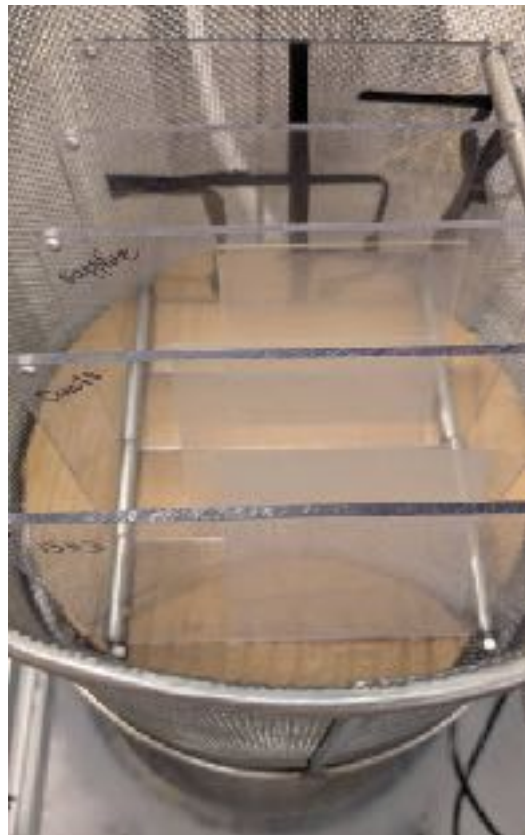
# Thermal stress test on pTP filter

## ▸ Vertical dipping test

- Simulation of the vertical mount PD module immersion process
- Using the CE test open mouth LN2 dewar and a shelf to maintain the position in the basket
- Steps:
  - Cleanup the dewar, top off with LN2
  - Drop the basket on top of the LN2 to ensure the gradual cooling process
  - Leave the samples on top of the LN2 surface for ~30 mins
  - Slowing dropping the basket into the LN2, takes about 10 mins
  - Leaving the samples in LN2 for about 18 hrs
  - Pulling the basket out of LN2, leaving the basket on top of LN2 for 30 mins
  - Pulling the basket up, halfway between the liquid and dewar top for 30 mins
  - Pulling the basket off the dewar, waiting for 30 mins until the surface temperature measured above 0 C
  - Applying fans to accelerate the drying for 1.5 hrs
  - Pull the samples into the dryer with ~30C drying temperature for 1 hr



# Thermal stress test (Vertical)





# Thermal stress test (horizontal)

## ► Horizontal dipping test

- Simulation of the horizontal mount PD module immersion process
- Almost exactly the same step as vertical, just with longer cooling time on top of LN2 for ~ 2 hrs
- The immersion process is imminent when touching the LN2 surface





# Thermal results and observation

- All substrates survived the thermal stress test with the controlled slow cooling process
- Significant changes on the coating after the cryogenic cycle
  - Most significant on Sapphire, least impact on B33
- Water gets under the coating during warming up

## **S4 Sapphire**

Before

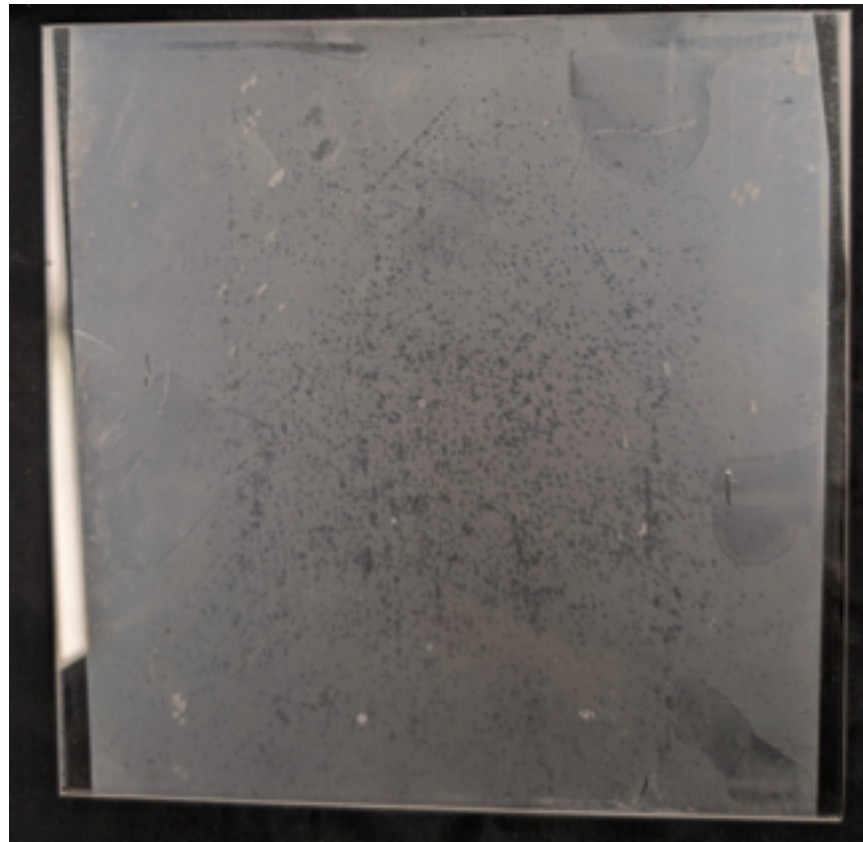
1st cold

2nd cold





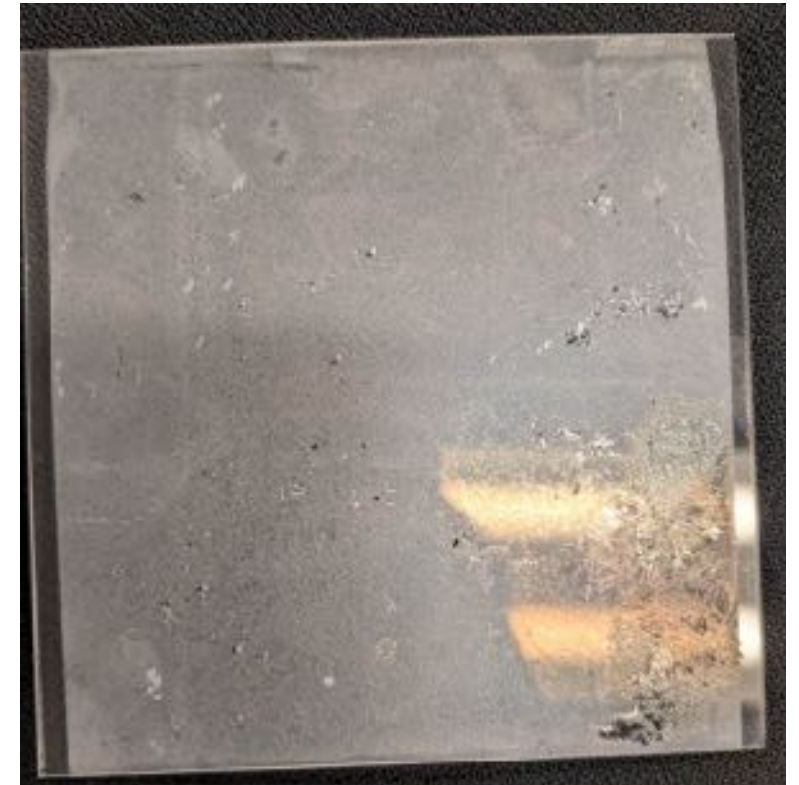
Before



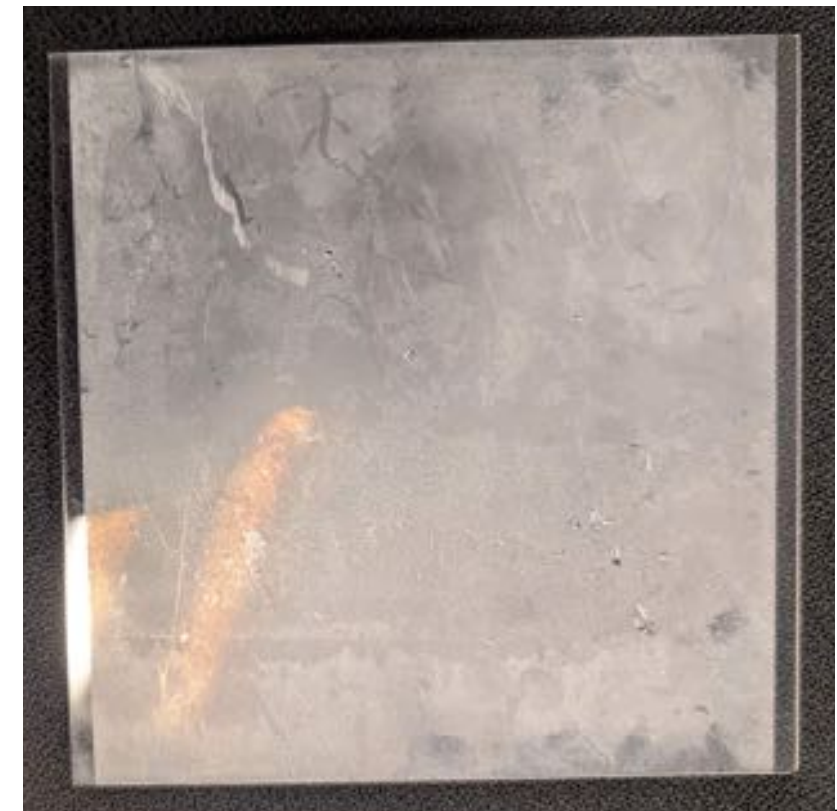
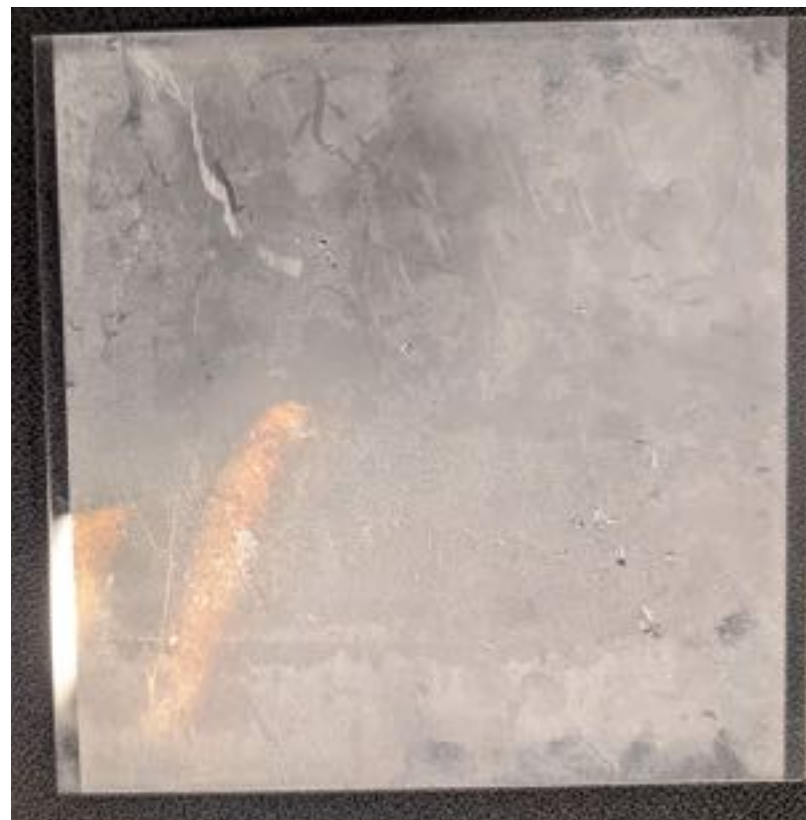
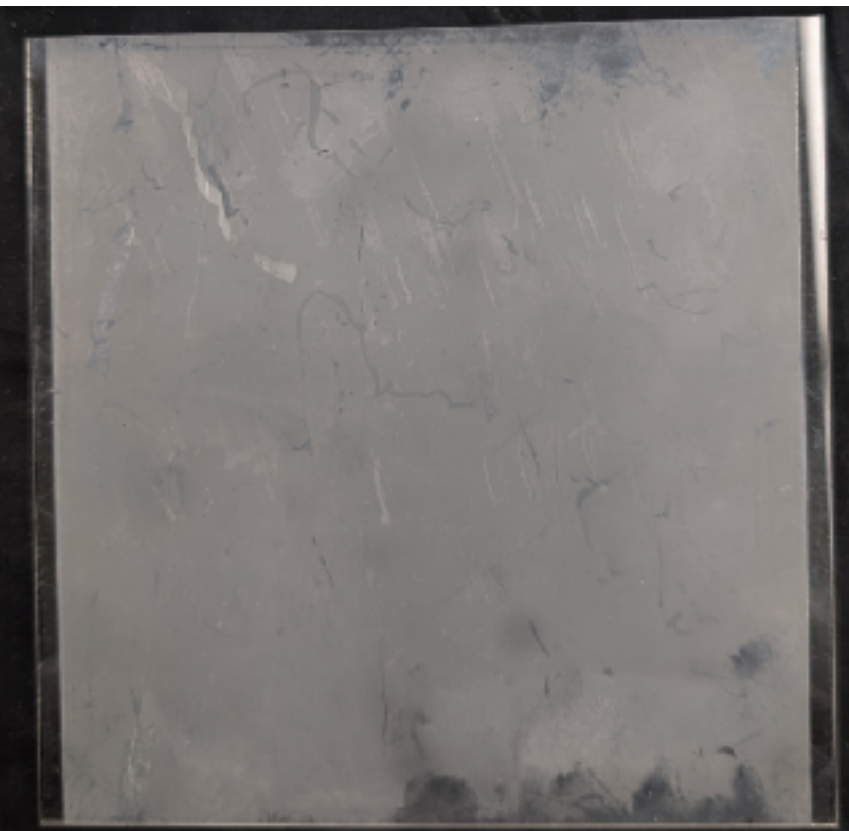
**S28 Quartz**  
1st cold



2nd cold



**Line 5 B33**





# S28 Quartz



# S4 Sapphire

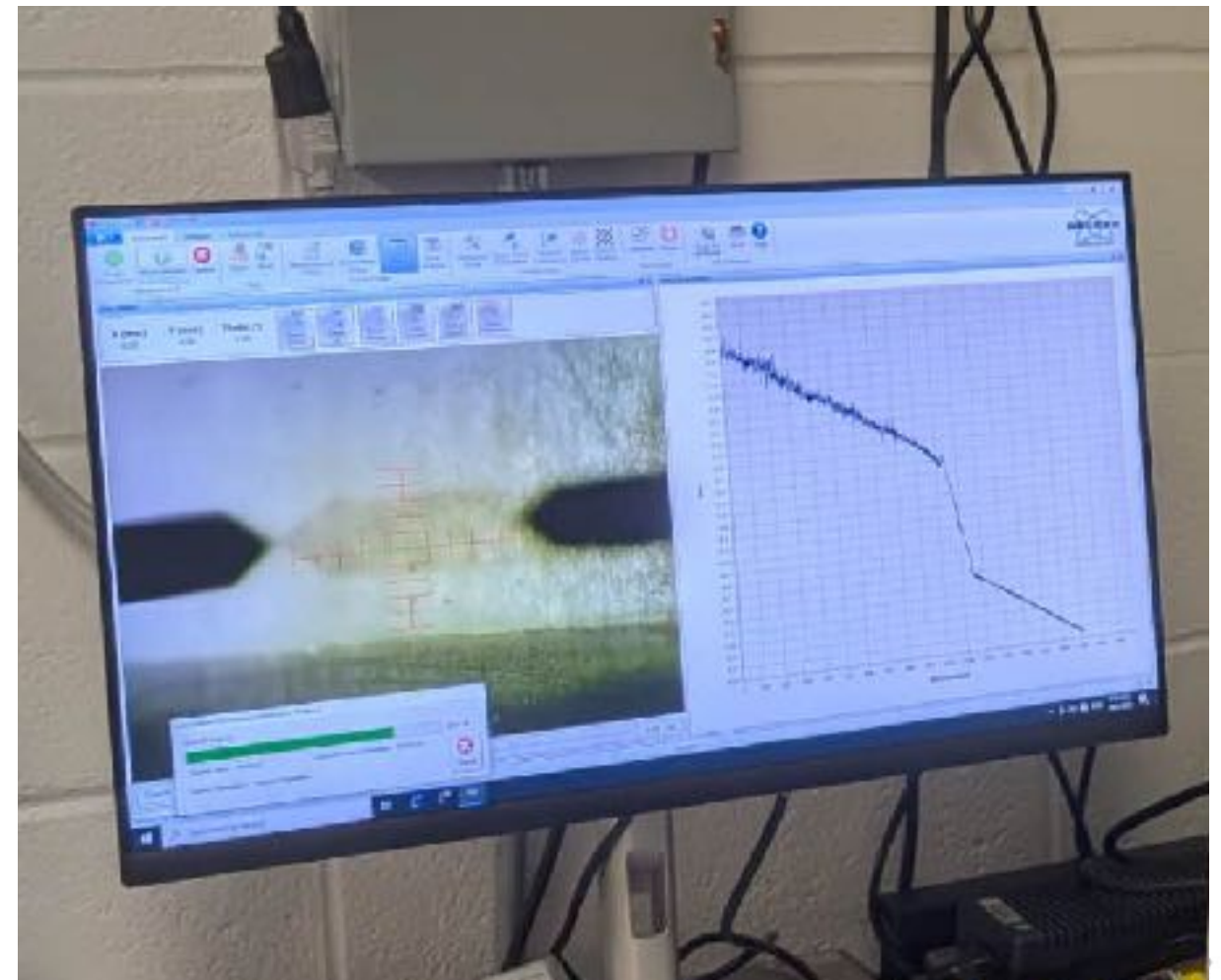
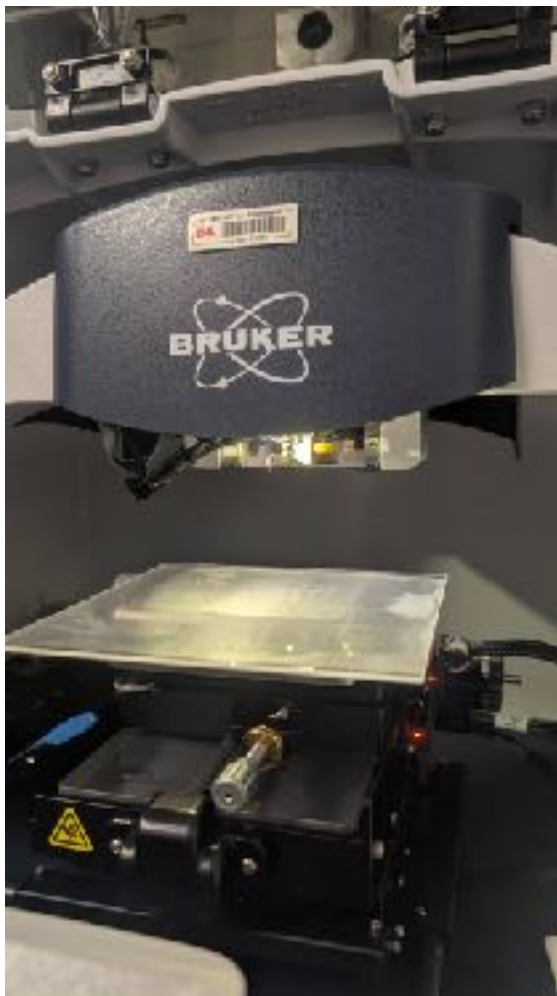




# Thickness measurement with profiler

## ► Coating thickness measurement using profiler at IO

- I learned the operation of the profilometer from Abdul
- Now I can conduct the thickness measurement independently
- Principle of operation
  - It is using a diamond probe with very little pressure on the surface  $\sim 3\text{mg}$  for the scanning
  - It is a differential measurement that requires a step
  - The the results requires a surface flatness correction(done by the software)

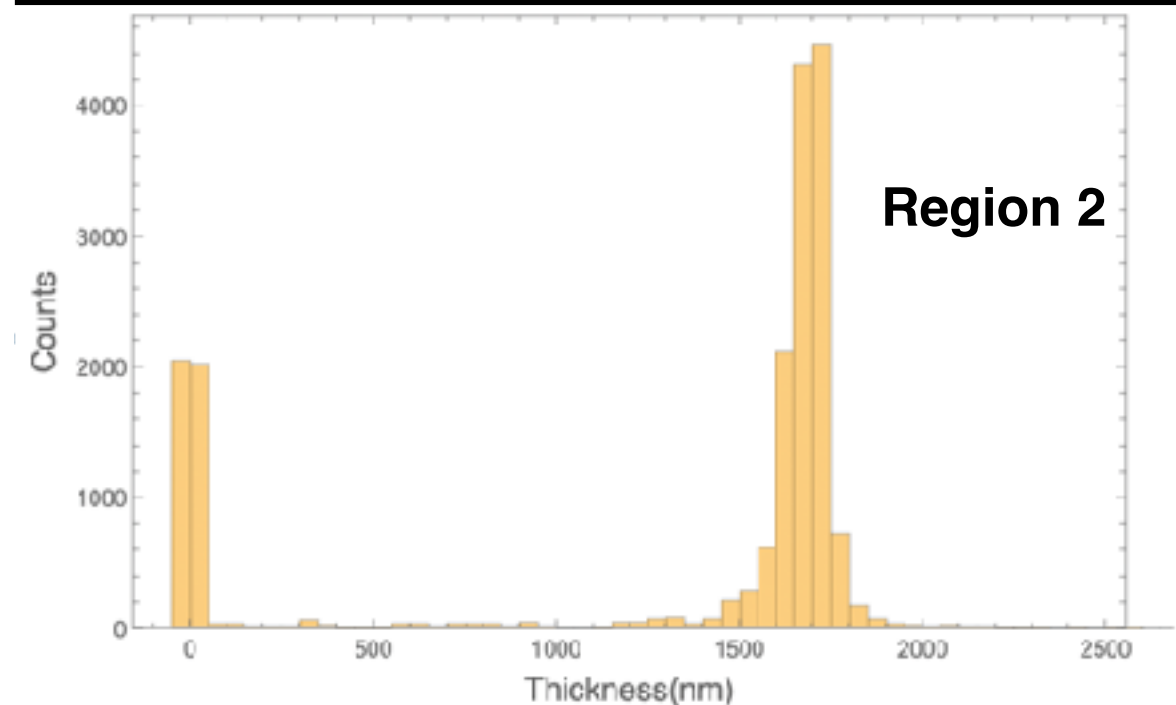
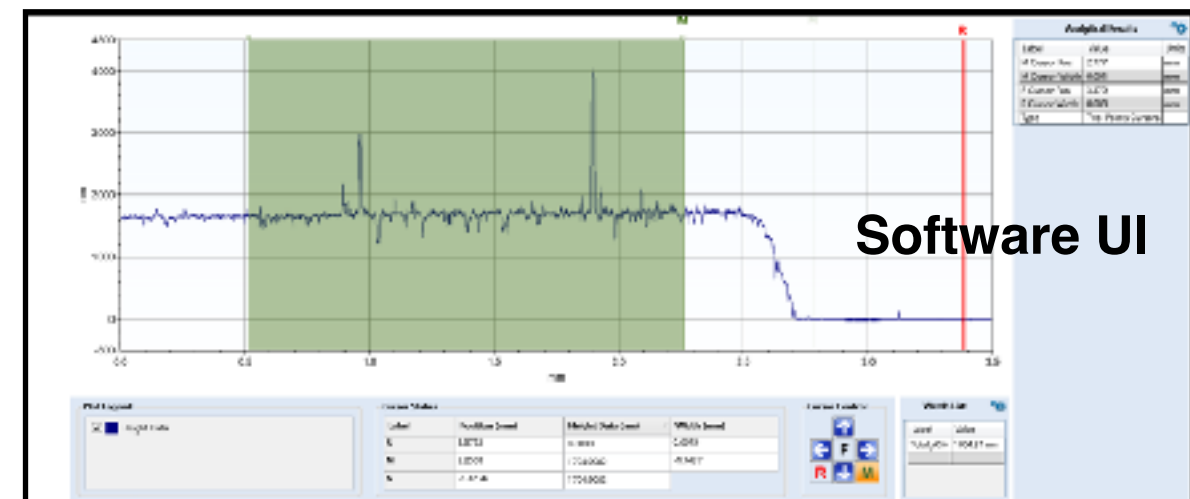
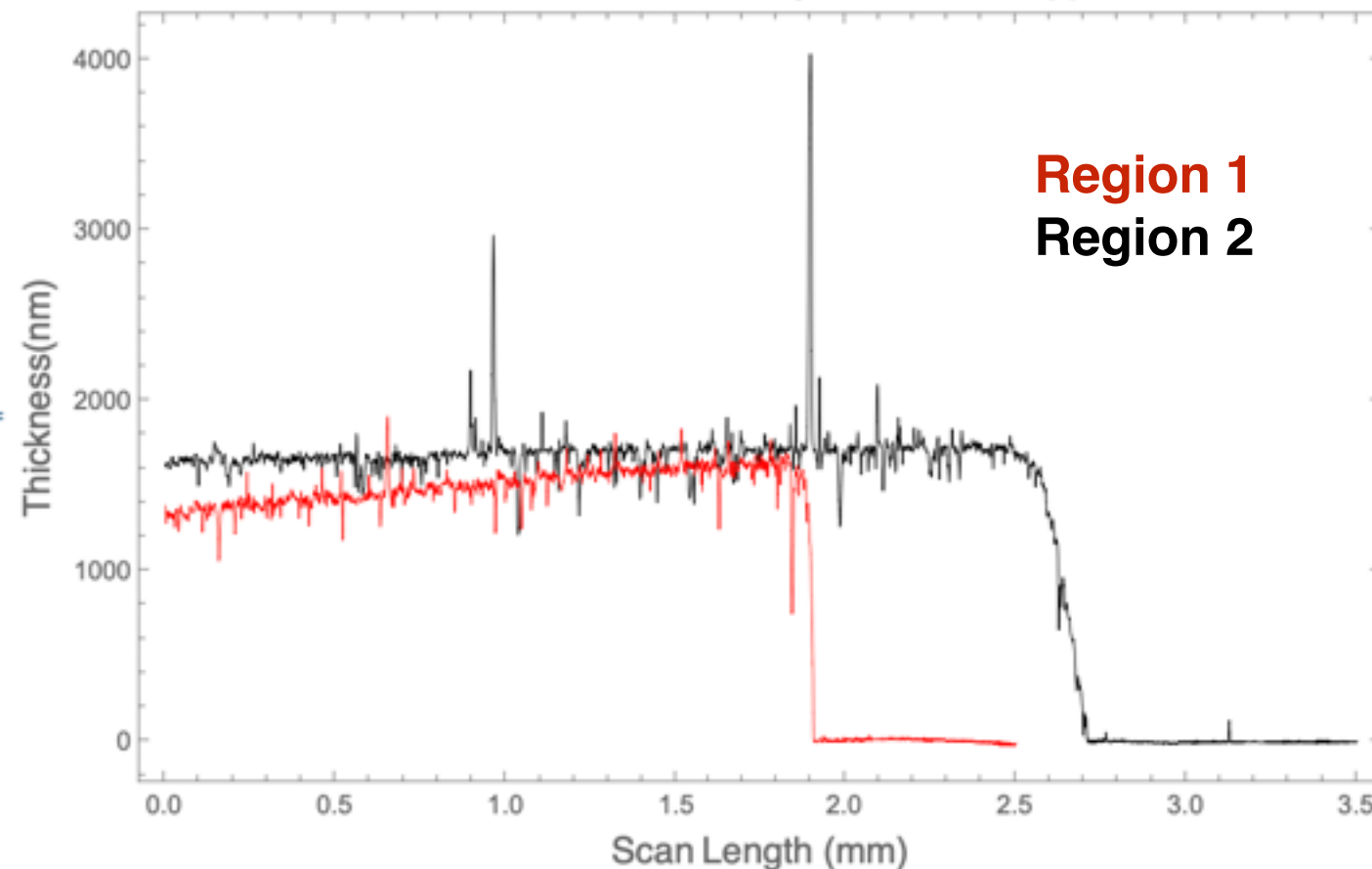


# Thickness measurement results

- I practiced the measurement on 3 samples with different substrates
- Scanned on multiple locations on the sample

## S2 sapphire

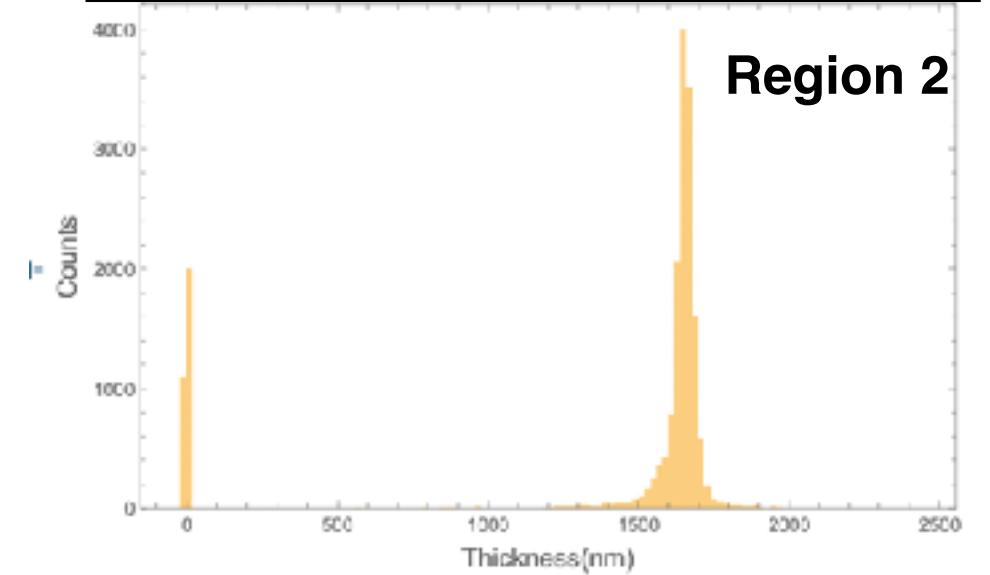
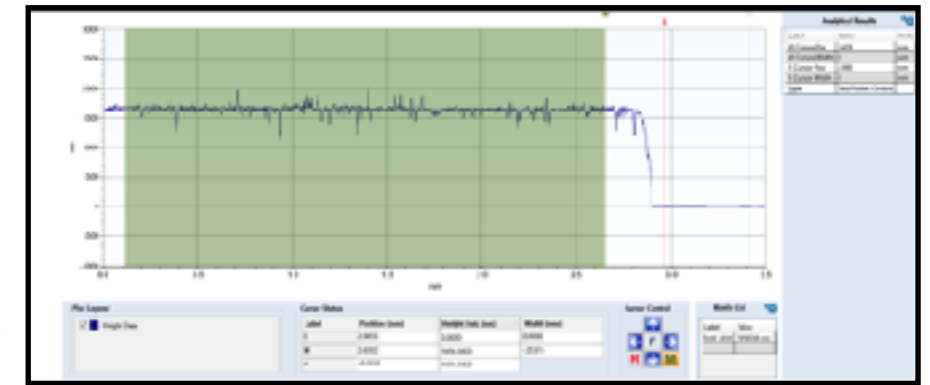
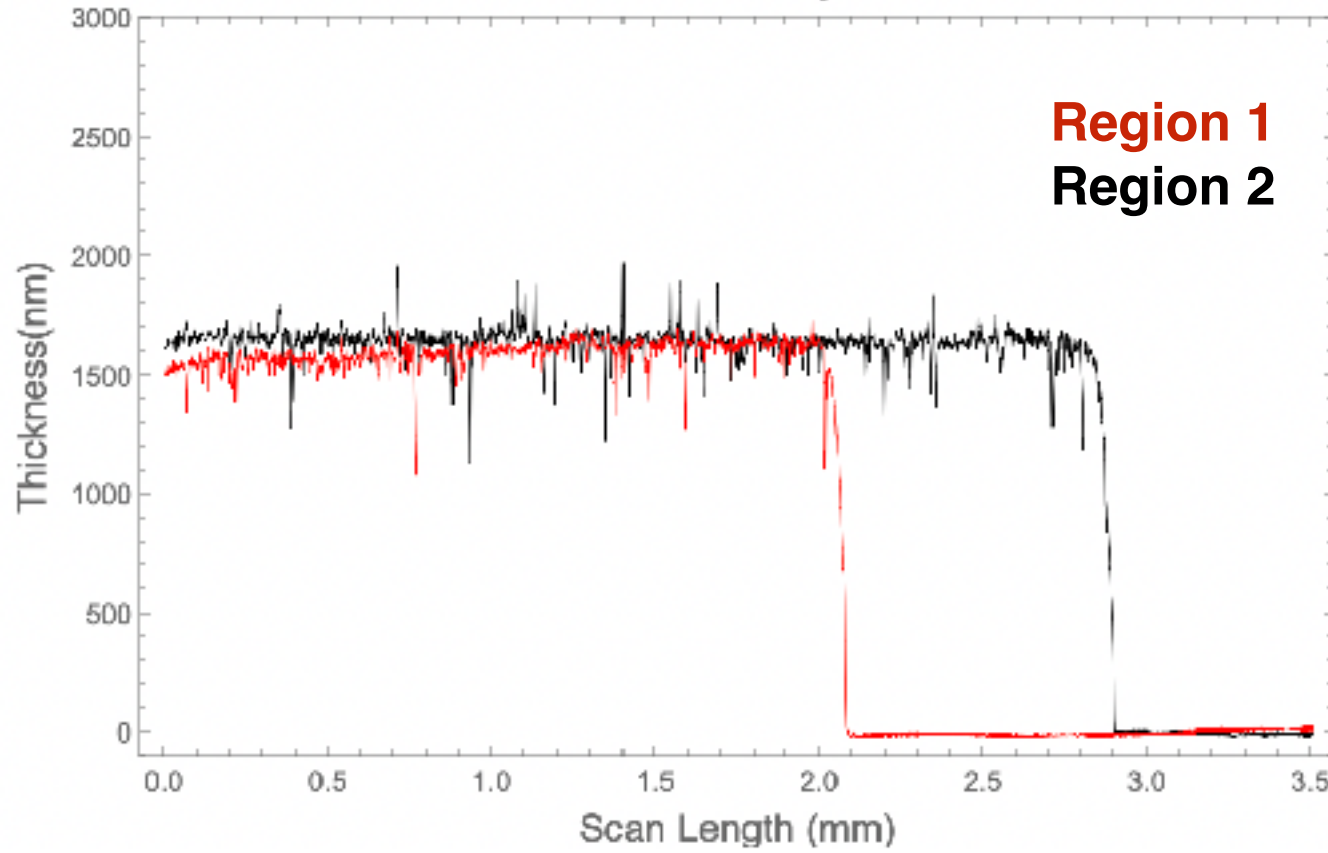
Thickness Measurement by Profiler S2 Sapphire





# S9 B33

Thickness Measurement by Profiler S9 B33



# S21 Quartz

Thickness Measurement by Profiler S21 Quartz

